





P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | R _{DS(ON)} Max | I _D Max T _A = +25°C |
|-------------------|---------------------------------|--|
| | 160mΩ @ V _{GS} = -4.5V | -2.4A |
| -20V | 210mΩ @ V _{GS} = -2.5V | -2.1A |

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters
- Motor Control

Features and Benefits

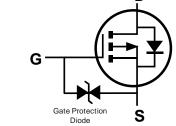
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

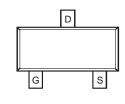
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish —Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ²³
- Terminals Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)







Internal Schematic



Top View

Top View

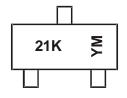
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|--------------|-------|--------------------|
| DMG2301LK-7 | SOT23 | 3,000/Tape & Reel |
| DMG2301LK-13 | SOT23 | 10,000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



21K = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Key

| Date Code Hoy | | | | | | | | | | | | |
|---------------|------|-----|------|------|-----|------|------|-----|------|------|-----|------|
| Year | 2016 | | 2017 | 2018 | | 2019 | 2020 |) | 2021 | 2022 | | 2023 |
| Code | D | | Е | F | | G | Н | | ı | J | | K |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|---|----------------|-----------------|-------|------|
| Drain-Source Voltage | | V_{DSS} | -20 | V |
| Gate-Source Voltage | | V_{GSS} | ±12 | V |
| Continuous Drain Current (Note 6) V _{GS} = -4.5V | I _D | -2.4 -1.9 | А | |
| Maximum Continuous Body Diode Forward Curre | ent (Note 6) | Is | -1.12 | Α |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = | 1%) | I _{DM} | -8 | Α |

Thermal Characteristics

| Characteristic | | Symbol | Value | Unit |
|--|--------------|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | | P_{D} | 0.84 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{\theta JA}$ | 150 | °C/W |
| Total Power Dissipation (Note 6) | | P _D | 1.40 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | R _{0JA} | 91 | °C/W |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified)

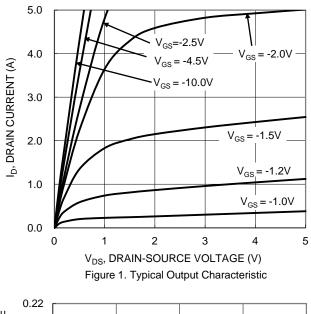
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | | | |
|--|---------------------|------|------|------|------|---|--|--|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | _ | | V | $V_{GS} = 0V, I_{D} = -250\mu A$ | | | |
| Zero Gate Voltage Drain Current (T _J = +25°C) | I _{DSS} | _ | _ | -10 | μA | $V_{DS} = -16V, V_{GS} = 0V$ | | | |
| Gate-Source Leakage | Igss | _ | _ | ±10 | μA | $V_{GS} = \pm 10V, V_{DS} = 0V$ | | | |
| ON CHARACTERISTICS (Note 7) | | | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.3 | -0.6 | -1.0 | V | $V_{DS} = V_{GS}, I_{D} = -250A$ | | | |
| | | | 136 | 160 | | $V_{GS} = -4.5V$, $I_D = -1.0A$ | | | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 183 | 210 | mΩ | $V_{GS} = -2.5V, I_D = -1.0A$ | | | |
| | | | 229 | 298 | | $V_{GS} = -1.8V, I_D = -0.2A$ | | | |
| Diode Forward Voltage | V_{SD} | _ | -0.8 | -1.2 | V | $V_{GS} = 0V, I_{S} = -1.0A$ | | | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | | | |
| Input Capacitance | C _{iss} | _ | 156 | | pF | ., ., ., ., | | | |
| Output Capacitance | Coss | _ | 36 | _ | pF | $V_{DS} = -6V, V_{GS} = 0V$ - f = 1.0MHz | | | |
| Reverse Transfer Capacitance | C _{rss} | _ | 28 | | pF | 1 = 1.01/11 12 | | | |
| Gate Resistance | R_g | _ | 41 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | | | |
| Total Gate Charge (V _{GS} = -4.5V) | Qg | _ | 1.6 | _ | nC | | | | |
| Total Gate Charge (V _{GS} = -10V) | Q_g | _ | 3.4 | _ | nC | $V_{DS} = -6V$, | | | |
| Gate-Source Charge | Q_{gs} | _ | 0.3 | _ | nC | $I_D = -2.2A$ | | | |
| Gate-Drain Charge | Q_{gd} | _ | 0.4 | _ | nC | | | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 3.2 | _ | ns | | | | |
| Turn-On Rise Time | t _R | _ | 7.4 | _ | ns | $V_{DS} = -6V$, $V_{GS} = -4.5V$, | | | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 11.0 | _ | ns | $R_{GEN} = 6 \Omega$, $I_D = -1A$ | | | |
| Turn-Off Fall Time | t _F | _ | 10.5 | _ | ns | 1 | | | |
| Reverse Recovery Time | t _{RR} | _ | 6.5 | _ | ns | 1 4 0 4 4 4 4 4 0 0 0 4 4 4 4 | | | |
| Reverse Recovery Charge | Q_{RR} | _ | 0.8 | _ | nC | I _F = -1.0A, di/dt = 100A/μs | | | |

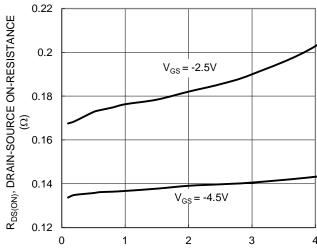
5. Device mounted on FR-4 PCB, with minimum recommended pad layout.

6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided. 7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.







I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

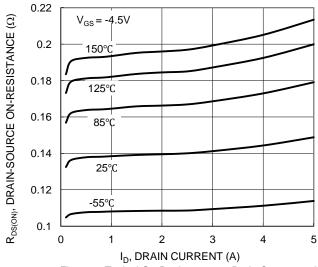
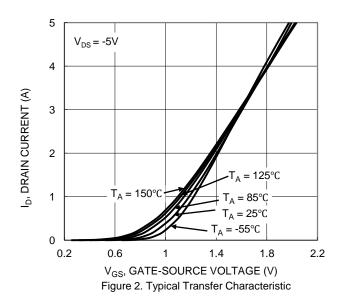
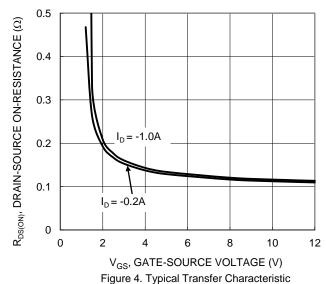
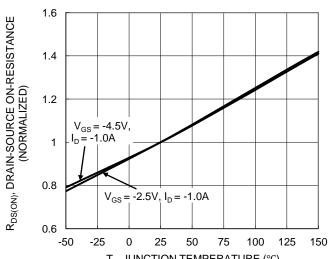


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature







T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Junction Temperature



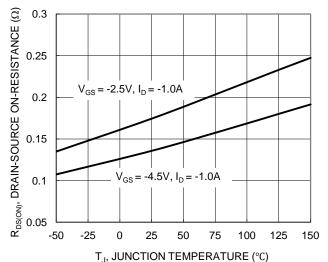
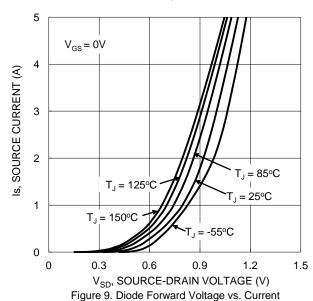
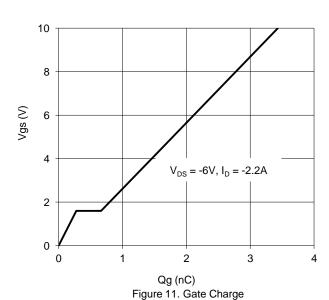


Figure 7. On-Resistance Variation with Junction Temperature





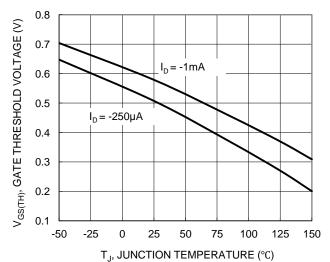


Figure 8. Gate Threshold Variation vs. Junction Temperature

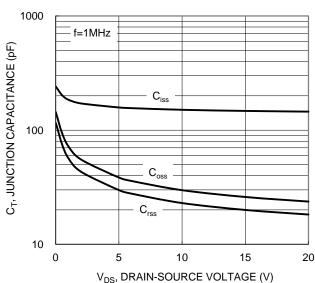


Figure 10. Typical Junction Capacitance

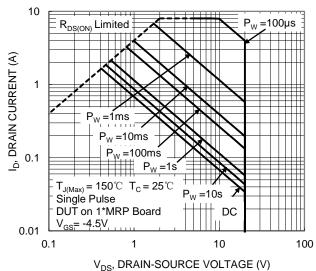


Figure 12. SOA, Safe Operation Area



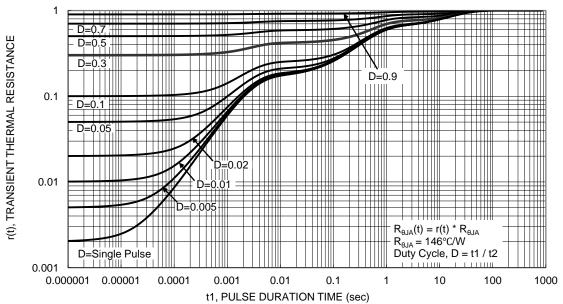


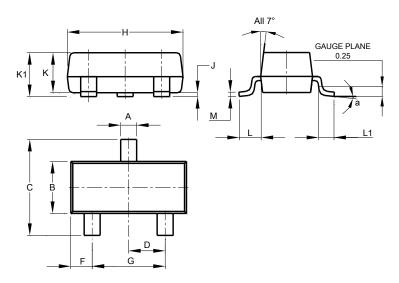
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

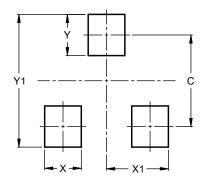


| SOT23 | | | | | | | | |
|----------------------|-------|-------|-------|--|--|--|--|--|
| Dim | Min | Max | Тур | | | | | |
| Α | 0.37 | 0.51 | 0.40 | | | | | |
| В | 1.20 | 1.40 | 1.30 | | | | | |
| С | 2.30 | 2.50 | 2.40 | | | | | |
| D | 0.89 | 1.03 | 0.915 | | | | | |
| F | 0.45 | 0.60 | 0.535 | | | | | |
| G | 1.78 | 2.05 | 1.83 | | | | | |
| Н | 2.80 | 3.00 | 2.90 | | | | | |
| 7 | 0.013 | 0.10 | 0.05 | | | | | |
| K | 0.890 | 1.00 | 0.975 | | | | | |
| K1 | 0.903 | 1.10 | 1.025 | | | | | |
| L | 0.45 | 0.61 | 0.55 | | | | | |
| L1 | 0.25 | 0.55 | 0.40 | | | | | |
| M | 0.085 | 0.150 | 0.110 | | | | | |
| а | 0° | 8° | | | | | | |
| All Dimensions in mm | | | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 2.0 |
| Х | 0.8 |
| X1 | 1.35 |
| Υ | 0.9 |
| Y1 | 2.9 |



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